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 Function, Pinout, and Drive Compatible With FCT and F Logic 	SN74FCT377T Q OR SO PACKAGE (TOP VIEW)
 Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions 	$ \overline{CE} \begin{bmatrix} 1 & 20 \end{bmatrix} V_{CC} \\ O_0 \begin{bmatrix} 2 & 19 \end{bmatrix} O_7 $
 Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics 	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
 I_{off} Supports Partial-Power-Down Mode Operation 	$O_2 \begin{bmatrix} 6 & 15 \\ 0_5 \end{bmatrix} O_5 \\ D_2 \begin{bmatrix} 7 & 14 \end{bmatrix} D_5$
 Matched Rise and Fall Times 	D ₃ [] 8 13 [] D ₄
 ESD Protection Exceeds JESD 22 2000-V Human-Body Model (A114-A) 200-V Machine Model (A115-A) 1000-V Charged-Device Model (C101) 	O ₃ [] 9 12 [] O ₄ GND [] 10 11] CP SN54FCT377T L PACKAGE
 Fully Compatible With TTL Input and Output Logic Levels 	(TOP VIEW)
 Clock Enable for Address and Data Synchronization Application 	
 Eight Edge-Triggered D-Type Flip-Flops CY54FCT377T 32-mA Output Sink Current 12-mA Output Source Current CY74FCT377T 	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$
 – 64-mA Output Sink Current – 32-mA Output Source Current 	⁶ ⁶ ⁹ ⁰ ⁰

description

The 'FCT377T devices have eight triggered D-type flip-flops with individual data (D) inputs. The common buffered clock (CP) inputs load all flip-flops simultaneously when the clock-enable (\overline{CE}) input is low. The register is fully edge triggered. The state of each D input at one setup time before the low-to-high clock transition is transferred to the corresponding flip-flop output (O). \overline{CE} must be stable only one setup time prior to the low-to-high clock transition for predictable operation.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



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TA	PAC	KAGE [†]	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING						
	QSOP – Q	Tape and reel	5.2	CY74FCT377CTQCT	FCT377C						
–40°C to 85°C	SOIC – SO	Tube	5.2	CY74FCT377CTSOC	FCT377C						
	3010 - 30	Tape and reel	5.2	CY74FCT377CTSOCT	FG13//G						
	QSOP – Q	Tape and reel	7.2	CY74FCT377ATQCT	FCT377A						
	SOIC – SO	Tube	7.2	CY74FCT377ATSOC	FCT377A						
	3010 - 30	Tape and reel	7.2	CY74FCT377ATSOCT	FCISITA						
	QSOP – Q	Tape and reel	13	13 CY74FCT377TQCT							
–55°C to 125°C	LCC – L	Tube	5.5	CY54FCT377CTLMB							
-55°C to 125°C	L00 - L	Tube	8.3	CY54FCT377ATLMB							

ORDERING INFORMATION

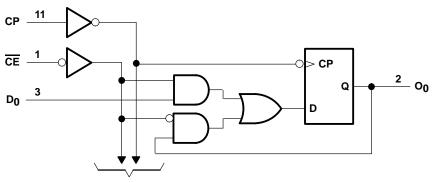
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS		OUTPUT	OPERATING MODE		
СР	CE	D	0			
↑	I	h	н	Load 1		
\uparrow	I	Ι	L	Load 0		
↑ X	h H	X X	No change	Hold		

H = High logic level, h = High logic level one setup time prior to the low-to-high clock transition, L = Low logic level, I = Low logic level one setup time prior to the low-to-high clock transition, X = Don't care, \uparrow = Low-to-high clock transition

logic diagram



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, T _A	65°C to 135°C
Storage temperature range, T _{stg}	. –65°C to 150°C

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		CY54FCT377T			CY7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-32	mA
IOL	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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		CY	54FCT37	7T	CY	74FCT37	7T			
PARAMETER	TEST CONDITIO	NS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$			-0.7	-1.2				V	
VIK	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$						-0.7	-1.2	v	
	$V_{CC} = 4.5 V$, $I_{OH} = -12 mA$		2.4	3.3						
Voн	$I_{OH} = -32 \text{ mA}$					2			V	
	$V_{CC} = 4.75 \text{ V}$ $I_{OH} = -15 \text{ mA}$					2.4	3.3			
) (V _{CC} = 4.5 V, I _{OL} = 32 mA			0.3	0.55				V	
VOL	V _{CC} = 4.75 V, I _{OL} = 64 mA						0.3	0.55	V	
V _{hys}	All inputs			0.2			0.2		V	
ų	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$				5			μΑ		
	$V_{CC} = 5.25 \text{ V}, V_{IN} = V_{CC}$							5	μΛ	
i	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$				±1					
lΗ	$V_{CC} = 5.25 \text{ V}, V_{IN} = 2.7 \text{ V}$							±1	μA	
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$				±1				μA	
ΙL	$V_{CC} = 5.25 \text{ V}, V_{IN} = 0.5 \text{ V}$							±1	μΑ	
· +	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$		-60	-120	-225				mA	
los‡	V _{CC} = 5.25 V, V _{OUT} = 0 V					-60	-120	-225	ША	
l _{off}	V _{CC} = 0 V, V _{OUT} = 4.5 V				±1			±1	μA	
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \leq 0.2 \text{ V},$	$V_{IN} \ge V_{CC} - 0.2 V$		0.1	0.2				mA	
lcc	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} \leq 0.2 \text{ V},$						0.1	0.2	ШA	
	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}\$, f_1 = 0, C$		0.5	2				mA		
∆ICC	$V_{CC} = 5.25 \text{ V}, V_{IN} = 3.4 \text{ V}\$, f_1 = 0,$	Outputs open					0.5	2	IIIA	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] Typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

* Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

		TEAT CONDITIO	20	CY	54FCT37	'7T	CY	74FCT37	7T	
PARAMETER		TEST CONDITIO	NS	MIN	түр†	MAX	MIN	түр†	MAX	UNIT
1005¶		Itputs open, g at 50% duty cycle IN $^{≥}$ V _{CC} − 0.2 V	, $\overline{CE} = GND$,		0.06	0.12				mA/
ICCD	V_{CC} = 5.25 V, C One bit switching $V_{IN} \le 0.2$ V or V					0.06	0.12	MHz		
		One bit switching at f ₁ = 5 MHz at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$		0.7	1.4				
	$V_{CC} = 5.5 V,$ Outputs open, $f_0 = 10 MHz,$ CE = GND	50% duty cycle	V_{IN} = 3.4 V or GND		1.2	3.4				
		Eight bits switching at f ₁ = 2.5 MHz at	$\begin{array}{l} V_{IN} \leq 0.2 \text{ V or} \\ V_{IN} \geq V_{CC} - 0.2 \text{ V} \end{array}$		1.6	3.2				
ı#		50% duty cycle	V_{IN} = 3.4 V or GND		3.9	12.2				4
IC#		One bit switching at $f_1 = 5 MHz$ at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$					0.7	1.4	mA
	V _{CC} = 5.25 V, Outputs open,	50% duty cycle	V_{IN} = 3.4 V or GND					1.2	3.4	
	<u>f</u> 0 = 10 MHz, CE = GND	Eight bits switching at	$\begin{array}{l} V_{IN} \leq 0.2 \ V \ or \\ V_{IN} \geq V_{CC} - 0.2 \ V \end{array} \end{array} \label{eq:VIN}$					1.6	3.2	
		f ₁ = 2.5 MHz at 50% duty cycle	V_{IN} = 3.4 V or GND					3.9	12.2	
Ci		-			5	10		5	10	pF
Co					9	12		9	12	pF

[†] Typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

 \P This parameter is derived for use in total power-supply calculations.

[#]IC = ICC + Δ ICC × D_H × N_T + I_{CCD} (f₀/2 + f₁ × N₁)

- Where:
- = Total supply current IC
- ICC = Power-supply current with CMOS input levels
- ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

 D_H = Duty cycle for TTL inputs high NT = Number of TTL inputs at D_H

- I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)
- = Clock frequency for registered devices, otherwise zero fo
- f₁ = Input signal frequency
- = Number of inputs changing at f1 N₁

All currents are in milliamperes and all frequencies are in megahertz.

Il Values for these conditions are examples of the I_{CC} formula.



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		CY54FC1 CY54FC1	-	CY74FC CY74FCT CY74FCT	UNIT			
		MIN	MAX	MIN	MAX			
tw	Pulse duration, CP high or low †	7		6		ns		
4	Satur time, high or low	Data before CP↑	2		2			
t _{su}	Setup time, high or low	CE before CP↑	3.5		3.5		ns	
.	Hold time, high or low	Data after CP↑	1.5		1.5		ns	
t _h H	Hold time, high or low	CE after CP↑	1.5		1.5			

[†] With one data channel switching, $t_{W(L)} = t_{W(H)} = 4$ ns and $t_{f} = t_{f} = 1$ ns.

switching characteristics over operating free-air temperature range (see Figure 1)

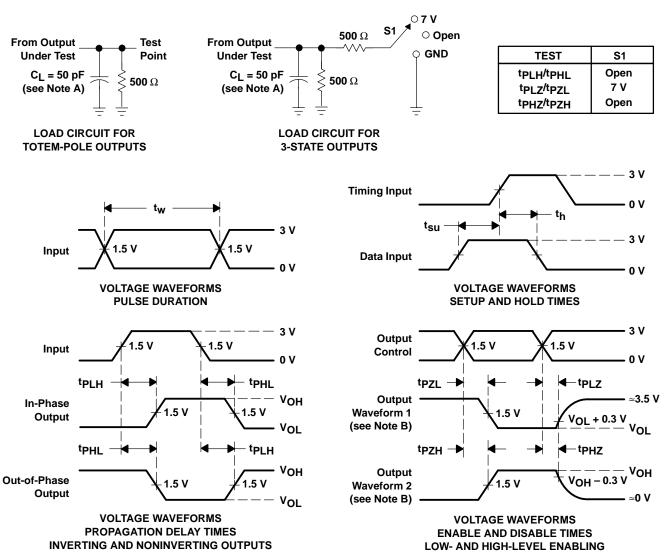
PARAMETER	FROM	то	CY54FC1	[377AT	CY54FC1	UNIT	
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
^t PLH	СР	0	2	8.3	2	5.5	20
^t PHL	CF	0	2	8.3	2	5.5	ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT377T		CY74FC	[377AT	CY74FC1	UNIT	
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	СР	0	2	13	2	7.2	2	5.2	200
^t PHL	CF	0	2	13	2	7.2	2	5.2	ns



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	-	Pins	-	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-9221902M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9221902M2A	Samples
5962-9221903M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9221903M2A CY54FCT 377CTLMB	Samples
CY54FCT377CTLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9221903M2A CY54FCT 377CTLMB	Samples
CY74FCT377ATQCT	ACTIVE	SSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT377A	Samples
CY74FCT377ATSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT377A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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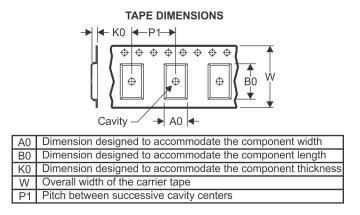
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT377ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

18-Aug-2014



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT377ATQCT	SSOP	DBQ	20	2500	367.0	367.0	38.0

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